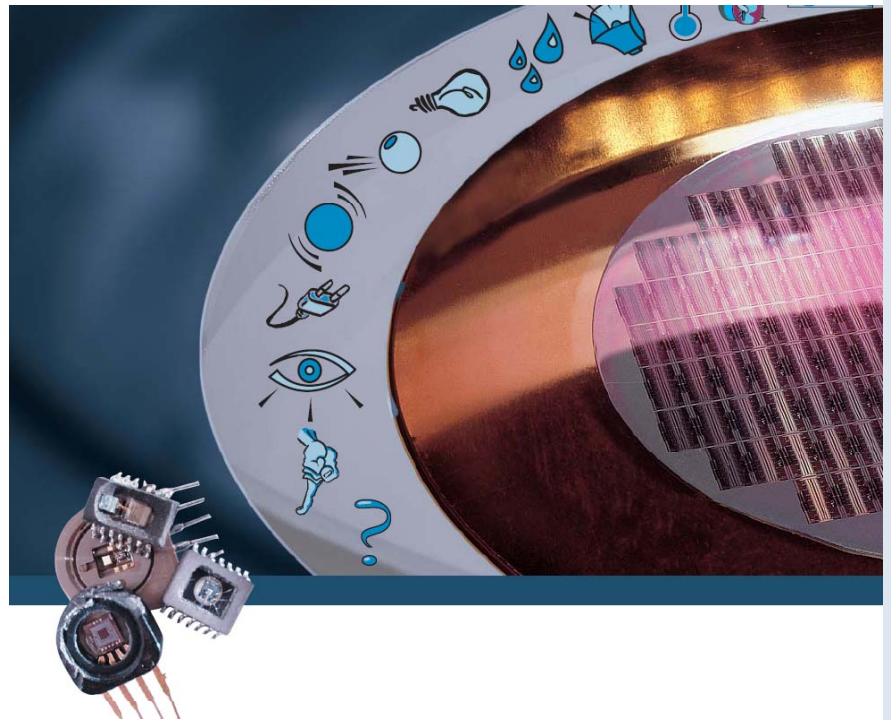


MEMS Testing and Metrology

**International
Workshop at**

SEMICON[®]
Europa2014

**Grenoble, France
October 7-8, 2014**



In cooperation with SEMI, MEMUNITY organizes the **2014 MEMS Testing and Metrology Workshop** at SEMICON Europa in Grenoble.

Discuss needs, challenges, and trends in MEMS development, testing, and metrology at a high level expert event.

Learn about recent advancements in measurement technology for characterizing mechanical and electrical properties of next generation MEMS devices and discuss about wafer level test strategies and standardization issues. Experience technical talks presented by industry experts from leading MEMS manufacturers, research institutes, universities, and equipment manufacturers.

Who should attend?

Technical professionals and executives involved in MEMS development, manufacturing and testing, from device manufacturers, MEMS integrators, research institutes, and equipment and technology suppliers.

Register now at:

www.semiconeuropa.org/node/2111

Early Bird Registration ends September 3, 2014

Organized by:



MEMS Testing and Metrology

International Workshop at

SEMICON[®]
Europa2014

Grenoble, France – October 7-8, 2014

Program

- | | |
|--|---|
| ■ Fast measurement of dimensions and material parameters of MEMS using SLDV | <i>M. Meinig, Fraunhofer ENAS, Chemnitz, Germany</i> |
| ■ Capabilities of white-light interference microscopy with respect to micro- and nanostructure measurement | <i>P. Lehmann, Kassel University, Germany</i> |
| ■ Optical metrology sheds light on shaping surface acoustic waves with phononic crystals in microfluidics | <i>J. Reboud, University of Glasgow, United Kingdom</i> |
| ■ Optical and interferometry measurement in industrial MEMS application | <i>M. Del Sarto, STMicroelectronics, Cornaredo, Italy</i> |
| ■ Exploring the Spatial and Temporal Limits of Homodyne Interferometry on NEMS Resonators | <i>J. Gorman, National Institute of Standards and Technology, Gaithersburg, USA</i> |
| ■ Characterization of packaged MEMS and Sensor Assemblies in the High-Frequency Range | <i>M. Bruck, SPEKTRA Schwingungstechnik und Akustik GmbH, Dresden, Germany</i> |
| ■ Wafer-Level Electro-Mechanical MEMS Testing and Calibration | <i>S. Muntwyler, FemtoTools AG, Buchs, Switzerland</i> |
| ■ MEMS characterization assisted by robots for microscopes | <i>V. Faivre, Imina Technologies SA, Lausanne, Switzerland</i> |
| ■ Measuring the impedance spectrum of a piezo actuator in the time domain | <i>P. Brandts, OCE Technologies B.V., Venlo, The Netherlands</i> |
| ■ Improved RF Design through precise 3D Near Field Scanning Measurement Techniques | <i>C. Hedayat, Fraunhofer ENAS, Paderborn, Germany</i> |
| ■ Response shaping and scale transition in dynamic systems with arrays of attachments | <i>J. Vignola, Catholic University of America, Washington DC, USA</i> |
| ■ Advanced Mechanical Stress Assessment on MEMS Components to Meet Reliability Demands | <i>D. Vogel, Fraunhofer ENAS, Chemnitz, Germany</i> |
| ■ Functionality Tests of 2D MEMS Scanners | <i>J. Janes, Fraunhofer ISIT, Itzehoe, Germany</i> |
| ■ MEMS testing with interferometric techniques employing Smart Pixel Camera | <i>Adam Styk, Warsaw University of Technology, Poland</i> |

Date and Location

October 7, 2:00 pm – 6:15 pm and
October 8, 9:00 am – 1:00 pm

Alpexpo, Grenoble, France

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